

100V N-Ch Power MOSFET

V_{DS}		100	V
$R_{DS(on),typ}$	$V_{GS}=10V$	7.0	m
$R_{DS(on),typ}$	$V_{GS}=4.5V$	9.1	m
I_D (Silicon Limited)		83	A
I_D (Package Limited)		70	A

Part Number	Package	Marking
HGD080N10AL	TO-252	GD080N10AL
HGI080N10AL	TO-251	GI080N10AL

Absolute Maximum Ratings at $T_J=25^{\circ}C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^{\circ}C$	83	A
		$T_C=100^{\circ}C$	53	
		$T_C=25^{\circ}C$	70	
Continuous Drain Current (Package Limited)			70	
Drain to Source Voltage	V_{DS}	-	100	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	260	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.4mH, T_C=25^{\circ}C$	245	mJ
Power Dissipation	P_D	$T_C=25^{\circ}C$	125	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	$^{\circ}C$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	R_{JA}	50	$^{\circ}C/W$
Thermal Resistance Junction-Case	R_{JC}	1.2	$^{\circ}C/W$

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Total Gate Charge	$Q_g(10V)$		32	-	
Gate to Source Charge	Q_{gs}	$V_{GS}=50V, I_D=20A, V_{GS}=10V$	- 6	-	nC
			- 4	-	
Turn on Delay Time	$t_{d(on)}$		- 7	-	
Rise time	t_r	$V_{DD}=50V, I_D=20A, V_{GS}=10V,$	- 4	-	
Turn off Delay Time	$t_{d(off)}$	$R_G=10 \Omega$	- 20	-	ns
Fall Time	t_f		- 3	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=20A$	- 0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50V, I_F=20A, di_F/dt=500A/\mu s$	- 40	-	ns
Reverse Recovery Charge	Q_{rr}		- 160	-	nC

Fig 1. Typical Output Characteristics

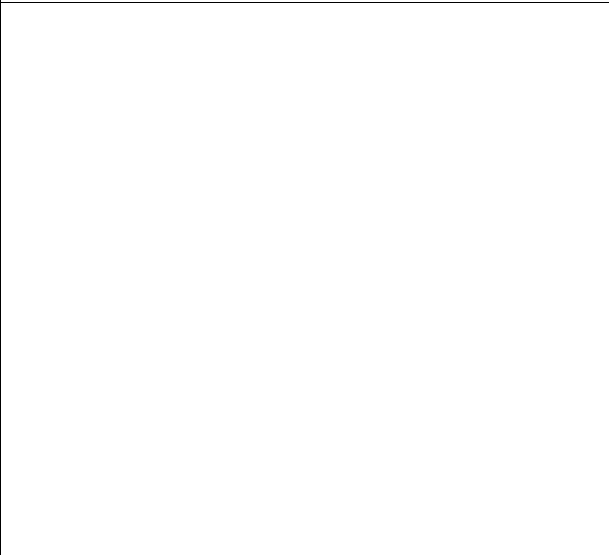
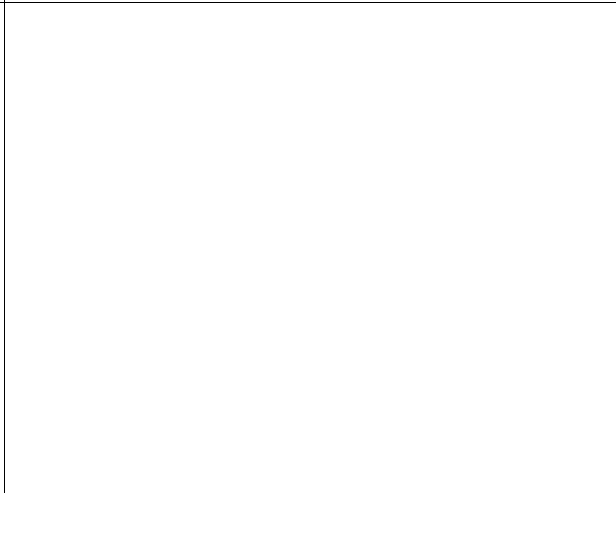


Figure 2. On-Resistance vs. Gate-Source Voltage



Fig

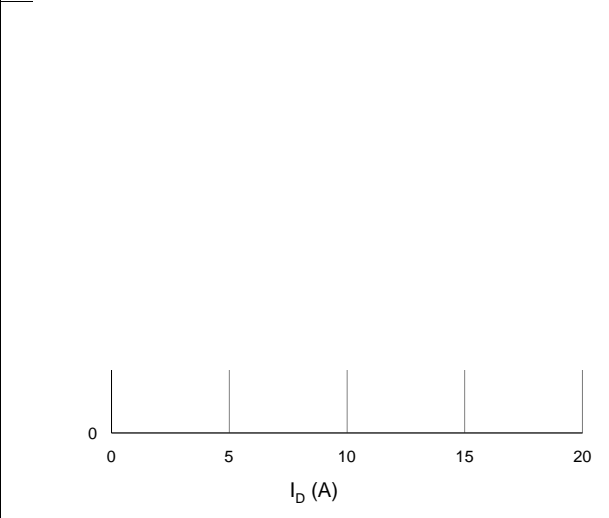


Figure 4. Normalized On-Resistance vs. Junction Temperature

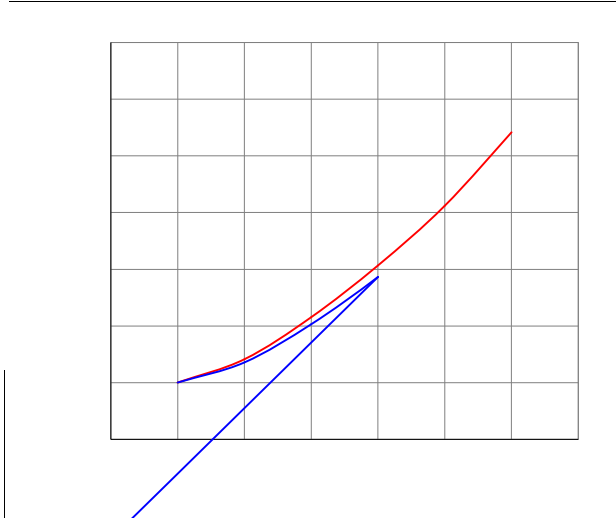


Figure 5. Typical Transfer Characteristics

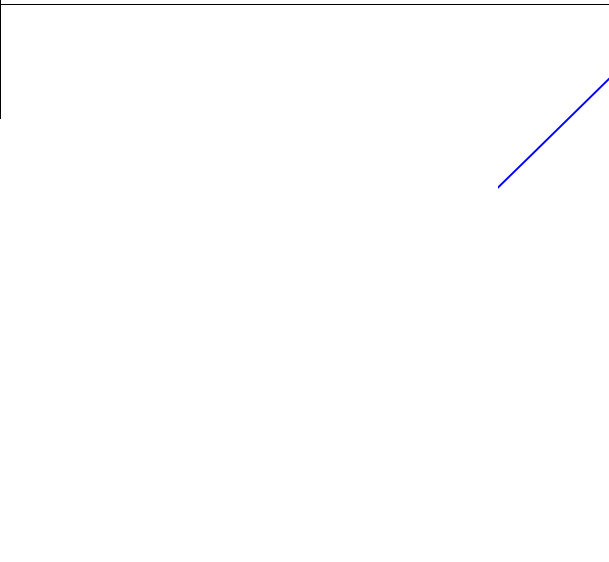


Figure 6. Typical Source-Drain Diode Forward Voltage

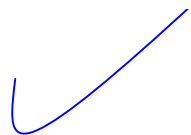
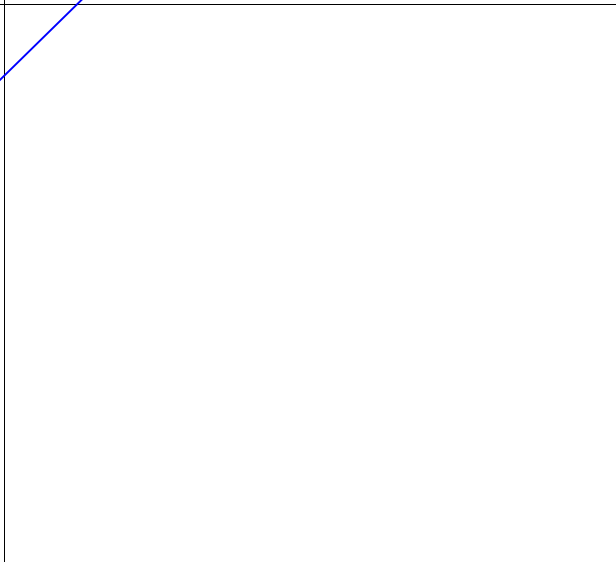


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

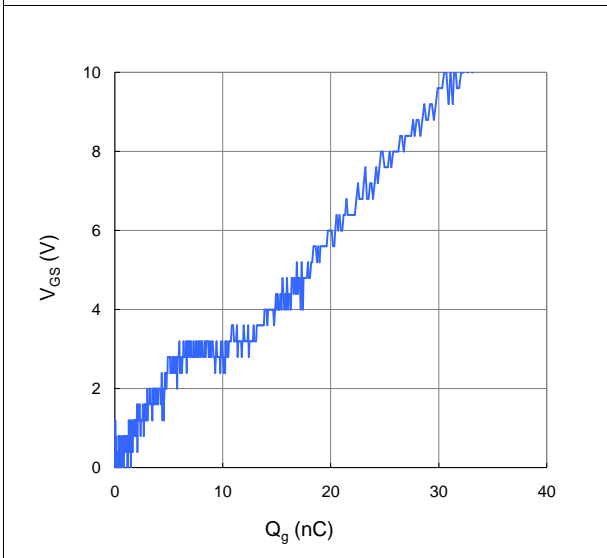


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

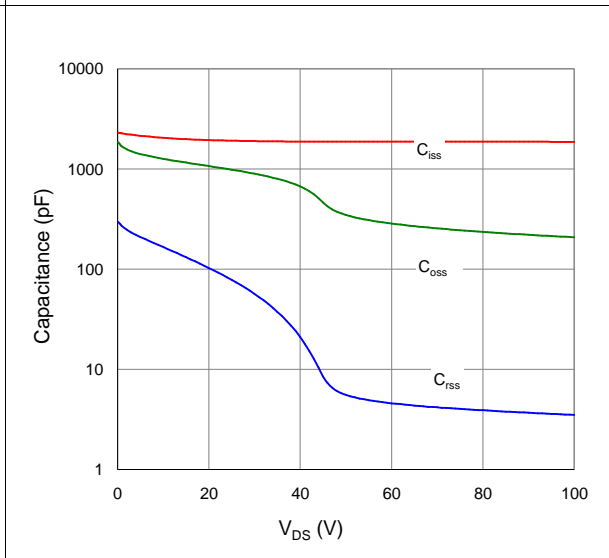


Figure 9. Maximum Safe Operating Area

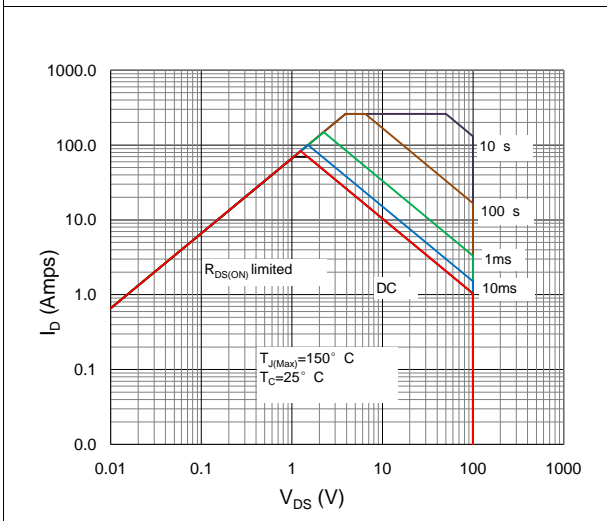


Figure 10. Maximum Drain Current vs. Case Temperature

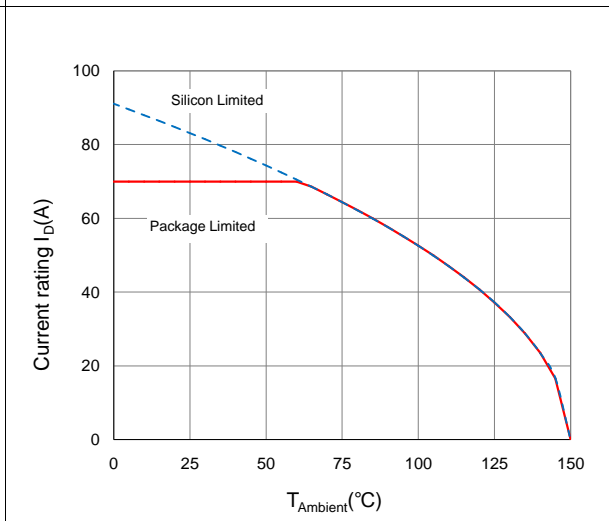
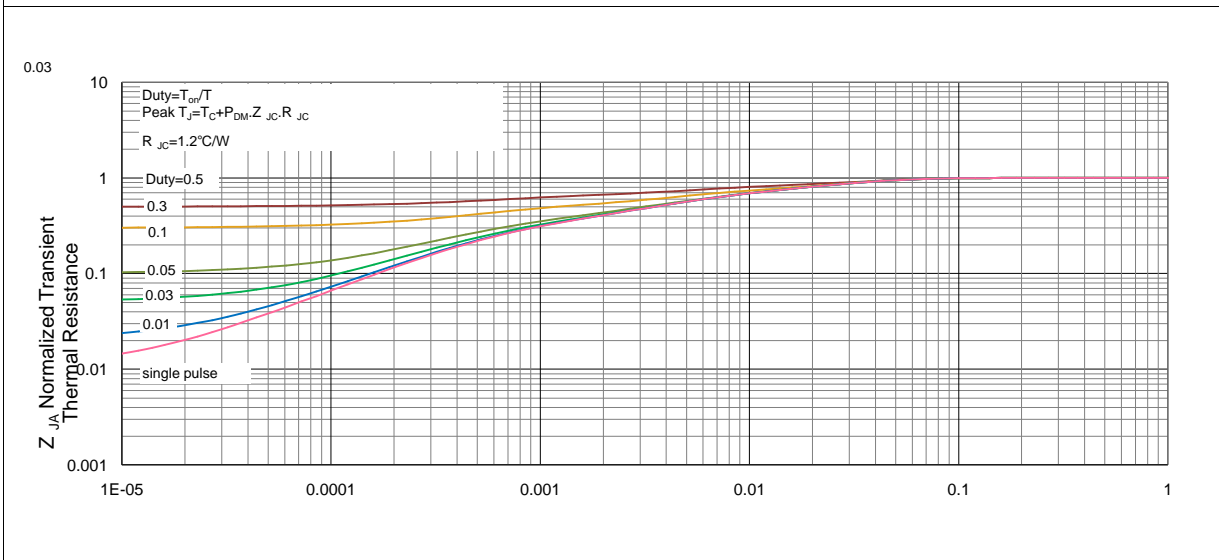
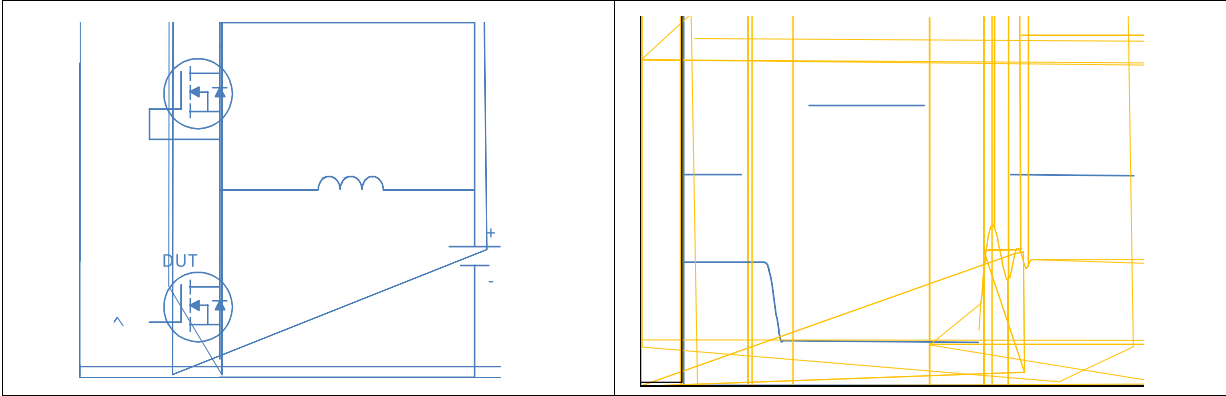


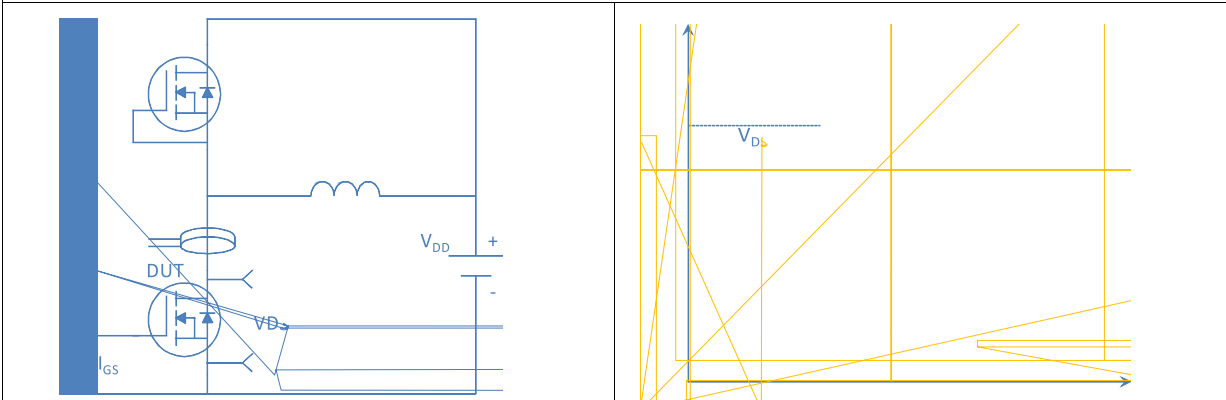
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



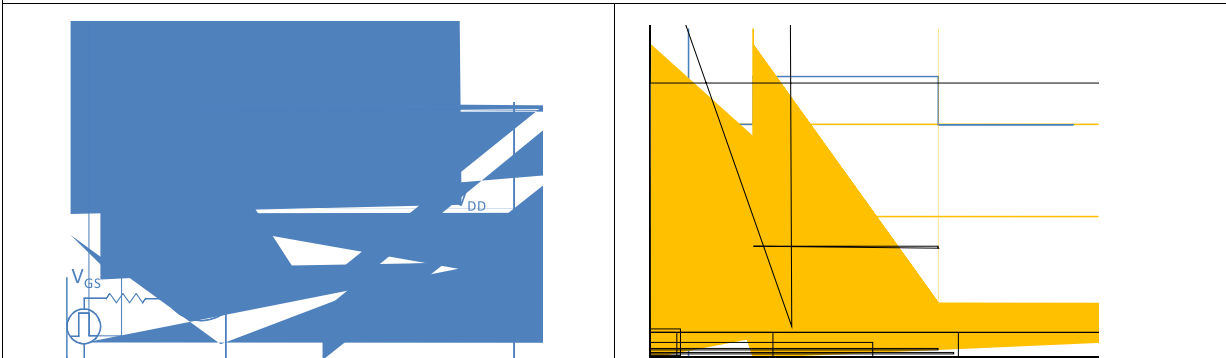
Inductive switching Test



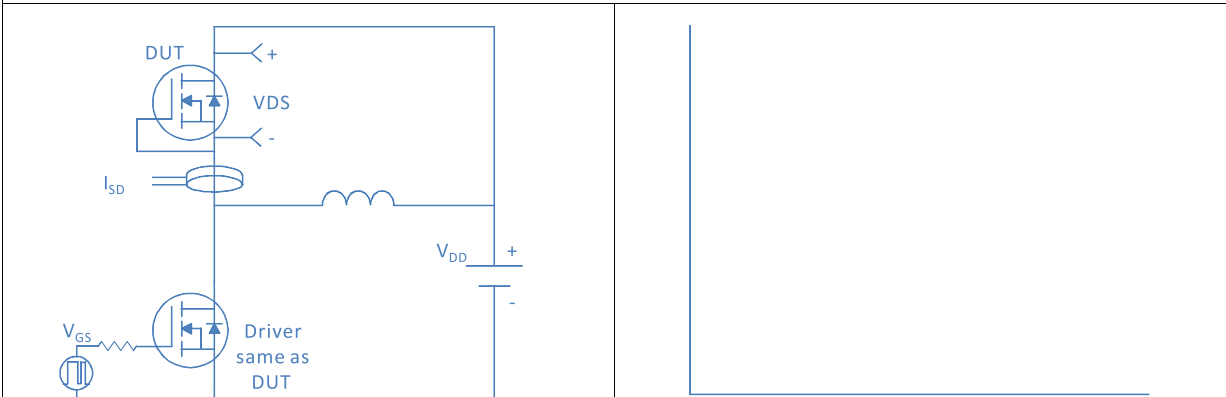
Gate Charge Test



Uclamped Inductive Switching (UIS) Test



Diode Recovery Test



Package Outline

TO-252, 3 leads



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
E	6.40	6.60	6.731
L	1.40	1.52	1.77
L1	2.743 REF		
L2	0.508 BSC		
L3	0.89	--	1.27
L4	0.64	--	1.01
L5	--	--	--
D	6.00	6.10	6.223

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E1	6.40	6.60	6.731
L1	2.743		REF
L2	0.508		BSC
L3	0.89		1.27
L4	0.64		1.01
L5			
D	6.00	6.10	6.223

